

Title (en)
BASE WEBS FOR PRINTED CIRCUIT BOARD PRODUCTION USING THE FOAM PROCESS AND ARAMID FIBERS

Title (de)
GRUNDBAHNEN FÜR DIE HERSTELLUNG VON LEITERPLATTEN DURCH SCHAUMVERFAHREN MIT ARAMIDFASERN

Title (fr)
BANDES DE BASE POUR LA PRODUCTION DE PLAQUETTES A CIRCUITS IMPRIMES UTILISANT LE GONFLEMENT DE LA MOUSSE ET DES FIBRES ARAMIDES

Publication
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Application
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Priority

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- US 10827898 A 19980701

Abstract (en)
[origin: WO9949118A1] A printed circuit board is made from at least one non-woven sheet or web layer comprising at least 10 % weight aramid fibers, with any balance substantially electrically non-conductive fibers, filler, and binder. The sheet or web is preferably made by the foam process, and at least about 10 % (e.g. at least about 60 %) of the aramid fibers utilized are aramid pulp fibers which have a number of advantages compared to the conventional straight aramid fibers. The web or sheet is preferably compressed so that it has a density of about 0.1-0.2 grams per cubic centimeter; and the web or sheet has a basis weight of between about 20-120 grams per square meter. The web may also have a substantially electrically non-conductive binder such as PVA or an epoxy resin. A printed circuit board made using the aramid layers of non-woven webs or sheets is otherwise conventional, including a pre-preg material, electrically conductive circuit elements, and electronics.

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IPC 8 full level
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